

## Electrostatic Discharged Protection Devices (ESD) Data Sheet

### Description

The LAD52C03L01-IP8 of Transient Voltage Suppressors (TVS) are designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computer, and PDAs. They offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. They are designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).

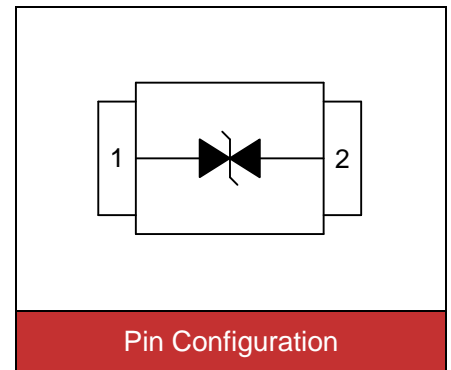


Contact : ±30kV  
Air : ±30kV



### Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOD523 surface mount package
- Working voltage: 3.3V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking:A3



### Maximum Ratings

Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	$V_{ESD}$	±30	kV
ESD voltage (Air discharge)		±30	
Lead soldering temperature	$T_L$	260	°C
Storage & operating temperature range	$T_{STG}, T_J$	-55~+150	°C

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ )

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	$V_{RWM}$				3.3	V
Reverse breakdown voltage	$V_{BR}$	$I_{BR}=1\text{mA}$	4.0			V
Reverse leakage current	$I_R$	$V_R=3.3\text{V}$			1	μA
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=1\text{A}$		5.2	7	V
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=8\text{A}$		9.5	12	V
Off state junction capacitance	$C_J$	0Vdc, f=1MHz		20		pF

## Typical Characteristics Curves

Figure 1. Pulse Waveforms

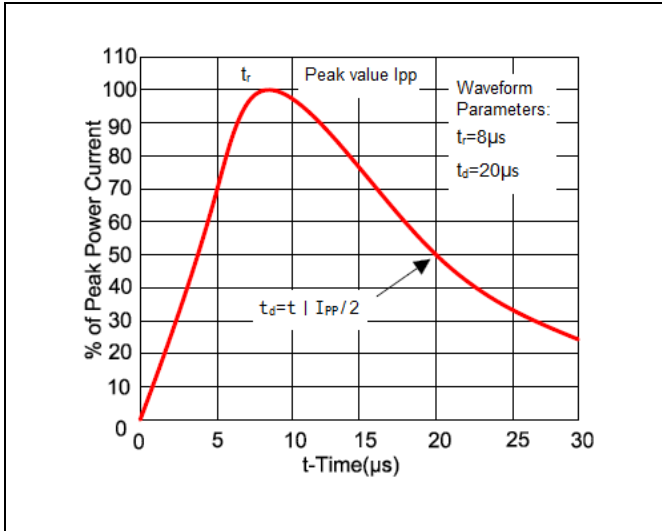


Figure 2. Clamping Voltage vs. Peak Pulse Current

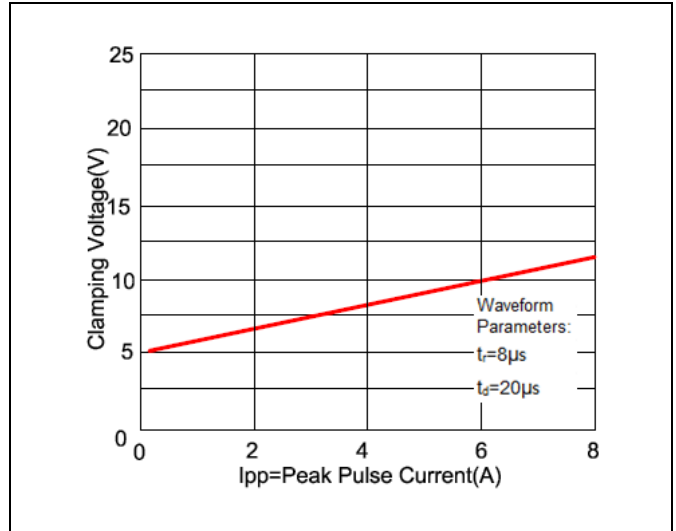


Figure 3. Capacitance vs. Reverse Voltage

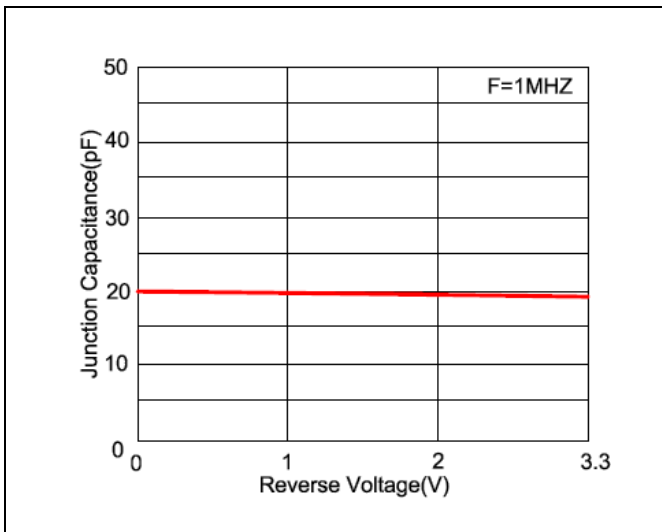
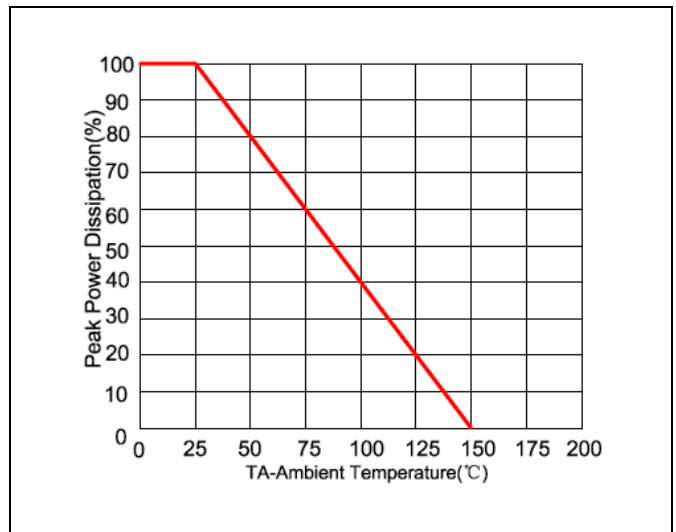
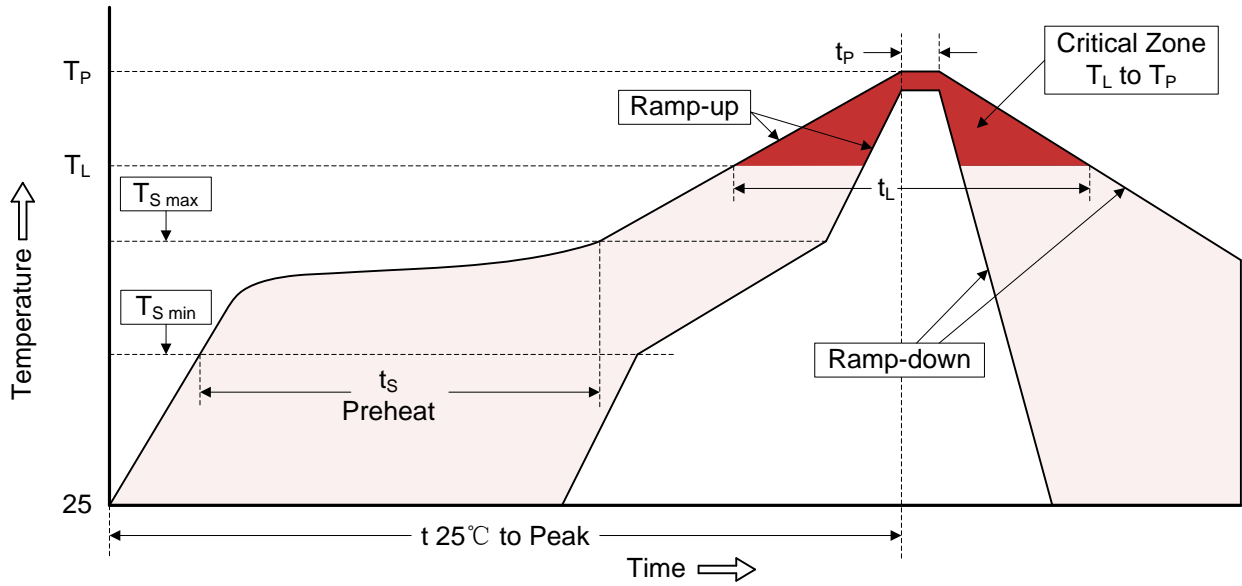


Figure 4. Power Derating Curve



**Recommended Soldering Conditions**

Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat -Temperature Min ( $T_{S\ min}$ ) -Temperature Max ( $T_{S\ max}$ ) -Time (min to max) ( $t_s$ )	150°C 200°C 60-180 seconds
$T_{S\ max}$ to $T_L$ -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature ( $T_L$ ) -Time ( $t_L$ )	217°C 60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

**Dimensions (SOD-523)**

Symbol	Dimension (mm)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.50	0.70	0.020	0.028
B	0.07	0.20	0.003	0.008
C	0.70	0.90	0.028	0.035
D	0.25	0.35	0.010	0.014
E	1.10	1.30	0.043	0.051
F	1.50	1.70	0.059	0.067
G	0.15	0.25	0.006	0.010

**Packaging**

Symbol	Dimension (mm)
W	8.00±0.30
P0	4.00±0.10
P1	2.00±0.10
P2	2.00±0.10
D0	Φ1.55±0.10
D1	Φ0.50±0.05
E	1.75±0.10
F	3.50±0.10
A	1.00±0.10
A0	0.50±0.10
B	1.80±0.10
B0	1.30±0.10
K	0.65±0.10
t	0.20±0.05

Symbol	Dimension (mm)
D	Φ178.0±2.0
D2	Φ13.0
W1	9.5
Quantity: 3000PCS	